This application note explains the overall delay affected by feedback trace delay. An LVCMOS ZDB is used as an example. Figure 1 shows a general LVCMOS Zero Delay Buffer (ZDB) schematic.

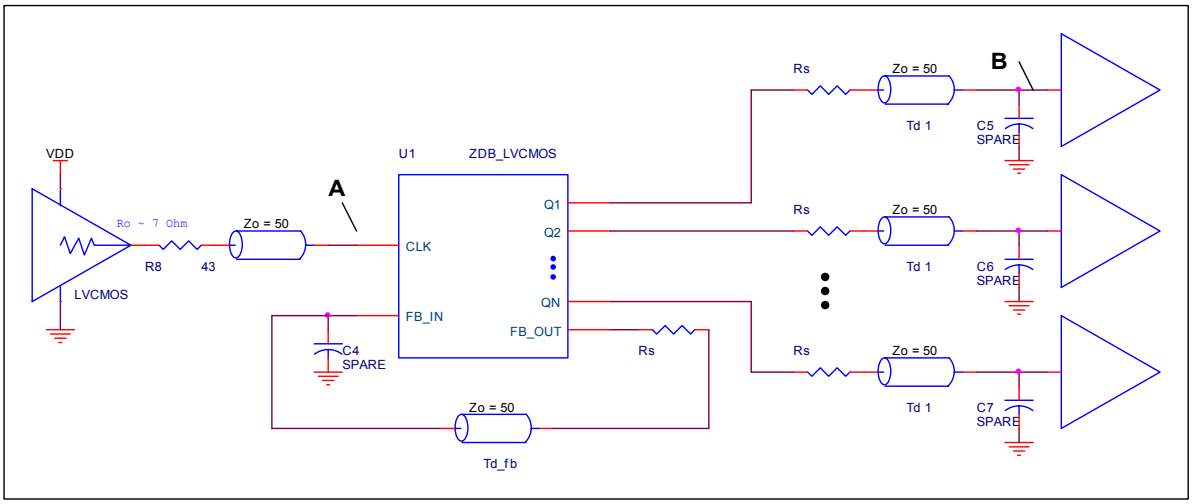

Figure 1 A ZDB Schematic Example

Delay between Point A to Point B
T_ab = Td1 – Td_fb + SPO + T_skew

Where
Td1 = trace delay of the outputs
Td_fb = trace delay of feedback path
SPO is static phase offset. SPO is given in the data sheet. Ideal SPO should be 0 second
T_skew is skew between the outputs. Ideal T_skew should be 0 second.

To explain how the output and feedback trace delays affects the overall delay, we assume the SPO and the skew are 0 second.

Case 1) Zero Delay
If Td1=Td_fb, then the T_ab = 0 (zero delay)

Case 2) Delay
If Td1 > Td_fb, then the T_ab > 0 (positive delay, or point B clock edge occur lagging point A clock edge)

Case 3) Advance
If Td1 < Td_fb, then the T_ab < 0 (negative delay, or point B clock edge occur leading point A clock edge)

The trace delay is approximately 100ps to 175ps per inch. Sometimes, it is difficult to control the trace delay. If possible, adding spare footprint for small value capacitors C4 to C7 will allow delay fine tuning after the board layout. Slightly increase the small C4 value has similar affect of adding delay to the feedback path.

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